



Material Content Data Sheet



Sales Product Name		IPI80N03S4L-03		Issued		2. August 2018		
MA#		MA000427164						
Package		PG-TO262-3-1		Weight*		1572.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	0.26	0.26	2561	2561
leadframe	inorganic material	phosphorus	7723-14-0	0.255	0.02		162	
	non noble metal	iron	7439-89-6	0.851	0.05		541	
	non noble metal	copper	7440-50-8	849.682	54.02	54.09	540188	540891
	non noble metal	aluminium	7429-90-5	5.630	0.36	0.36	3579	3579
wire	non noble metal	aluminium	7429-90-5	5.630	0.36	0.36	3579	3579
encapsulation	organic material	carbon black	1333-86-4	8.813	0.56		5603	
	plastics	epoxy resin	-	96.940	6.16		61630	
	inorganic material	silicondioxide	60676-86-0	481.762	30.63	37.35	306283	373516
leadfinish	non noble metal	tin	7440-31-5	15.198	0.97	0.97	9662	9662
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.064	0.00		41	
	noble metal	silver	7440-22-4	0.080	0.01		51	
	non noble metal	lead	7439-92-1	3.055	0.19	0.20	1942	2034
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		20	
	non noble metal	iron	7439-89-6	0.106	0.01		68	
	non noble metal	copper	7440-50-8	106.210	6.75	6.76	67523	67611
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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